

Title (en)
SINTERED BODY AND METHOD FOR PRODUCING SAME; SLIDING MEMBER, FILM-FORMING MATERIAL AND DIE FOR HOT EXTRUSION MOLDING EACH USING SUCH SINTERED BODY; AND HOT EXTRUSION MOLDING APPARATUS AND HOT EXTRUSION MOLDING METHOD EACH USING SUCH DIE FOR HOT EXTRUSION MOLDING

Title (de)
SINTERKÖRPER UND HERSTELLUNGSVERFAHREN DAFÜR, FILMBILDENDES MATERIAL UND DÜSE ZUM HEISSEXTRUSIONSFORMEN, JEWEILS UNTER VERWENDUNG EINES DERARTIGEN SINTERKÖRPERS UND HEISSEXTRUSIONSFORMGEBUNGSVORRICHTUNG UND HEISSEXTRUSIONSFORMGEBUNGSVERFAHREN, JEWEILS UNTER VERWENDUNG EINER DERARTIGEN DÜSE ZUM HEISSEXTRUSIONSFORMEN

Title (fr)
CORPS FRITTE ET SON PROCEDE DE FABRICATION ; ELEMENT COULISSANT, MATERIAU FILMOGENE ET FILIERE POUR MOULAGE PAR EXTRUSION A CHAUD UTILISANT CHACUN LE CORPS FRITTE ; ET DISPOSITIF DE MOULAGE PAR EXTRUSION A CHAUD ET PROCEDE DE MOULAGE PAR EXTRUSION A CHAUD UTILISANT CHACUN LADITE FILIERE POUR MOULAGE PAR EXTRUSION A CHAUD

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Application
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Priority
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Abstract (en)
There can be provided a sliding member, a film-forming material and a die for hot extrusion molding, that have high strength, high hardness, high toughness and high sliding properties under an atmosphere at about 400 to 600°C, as well as a hot extrusion molding device using the die for hot extrusion molding, by using a sintered body comprising 58% by mass or more and 92.5% by mass or less of TiCN, 0.01% by mass or more and 1% by mass or less of Ti, 0.01% by mass or more and 2% by mass or less of TiC, and 0.01% by mass or more and 2% by mass or less of TiN, the balance being TaC, Ni and Cr.

IPC 8 full level
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